Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.087”**

**ANODE**

**.076 x .076”**

**.087”**

**Top Material: Al**

**Backside Material: Ag**

**Bond Pad Size = .076 X .076”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .087” X .087 DATE: 11/10/21**

**MFG: MICROSEMI THICKNESS .011” P/N: 1N6492**

**DG 10.1.2**

#### Rev B, 7/1